



SOT1305-1

HSOP44: plastic, heatsink small outline package; 44 leads;
low stand-off height

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HSOP44
Package type industry code	HSOP44
Package style descriptive code	HSOP (heatsink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	31-5-2011

Table 1. Package summary

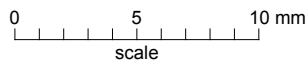
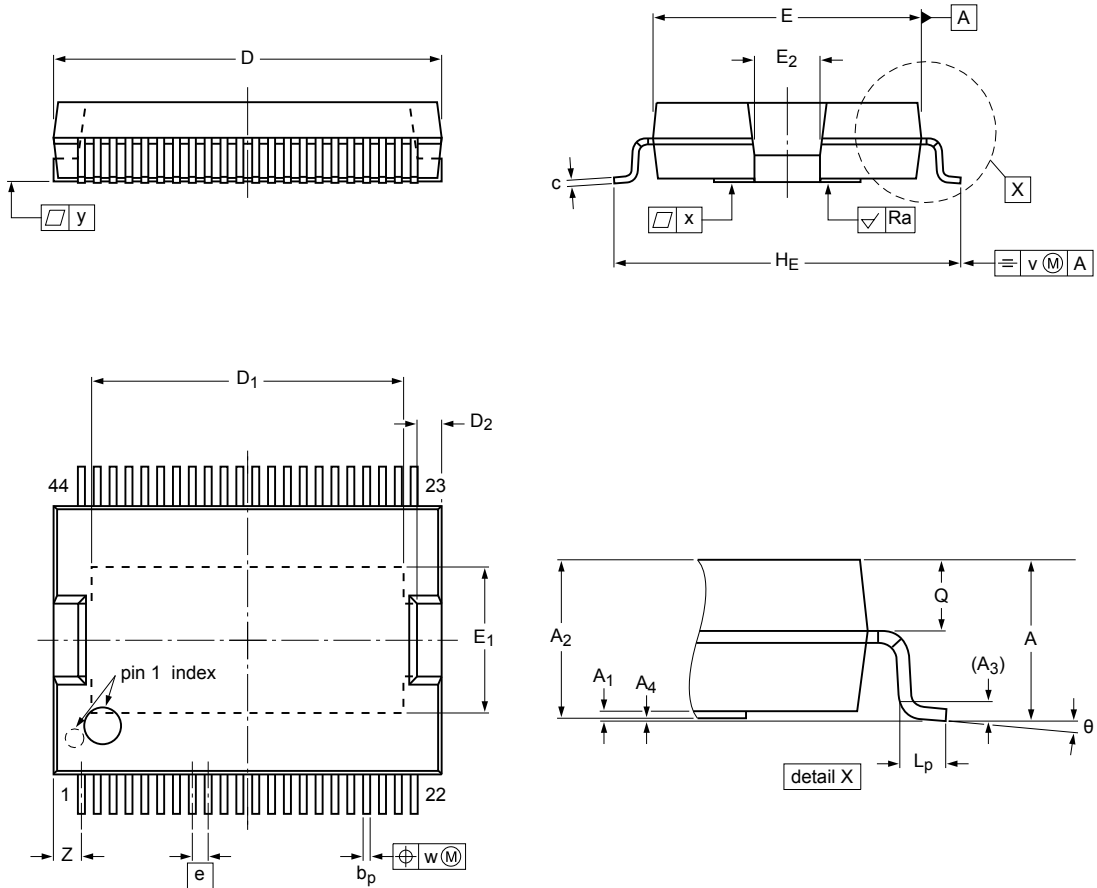
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	15.8	-	16	15.9	mm
E	package width	10.9	-	11	11.1	mm
A	seated height	3.05	-	3.3	3.6	mm
A ₂	package height	3.2	-	3.3	3.5	mm
e	nominal pitch	-	-	0.65	-	mm
n ₂	actual quantity of termination	-	-	44	-	



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2. Package outline

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Ra	Z	θ
1.1 μm	1.30	8°
0.6 μm	1.13	4°
0.1 μm	0.95	0°

Dimensions

Unit	A	A ₁	A ₂	A ₃	A ₄ ⁽¹⁾	bp	c	D ⁽²⁾	D ₁	D ₂	E ⁽²⁾	E ₁	E ₂	e	H _E	L _p	Q	v	w	x	y	
max	3.60	0.3	3.5		0.10	0.38	0.32	16.0	13.0	1.1	11.1	6.2	2.9		14.5	1.10	1.50					
nom	3.30	0.2	3.3	0.35	0.05	0.30	0.25	15.9	12.8	1.0	11.0	6.0	2.7	0.65	14.2	0.95	1.45	0.25	0.12	0.03	0.1	
min	3.05	0.1	3.2		0.00	0.25	0.23	15.8	12.6	0.9	10.9	5.8	2.5		13.9	0.80	1.40					

Note

- Limits per individual lead.
- Plastic or metal protrusions of 0.25 mm maximum per side are not included.

sot1305-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1305-1					11-04-28 11-05-02

Fig. 1. Package outline HSOP44 (SOT1305-1)

3. Legal information

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